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Docket No.: 0033-1048PUS1
(PATENT)

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Patent Application of:
Shinji TAKASE et al.

International Application No.: PCT/JP2004/019164

Application No.: NEW

Art Unit: N/A

Filed: December 27, 2005

Examiner: Not Yet Assigned

For: **METHOD OF RESIN SEALING OF
ELECTRONIC COMPONENT AND MOLD
USED IN THE METHOD**

PRELIMINARY AMENDMENT

MS Assignment Recordation Services
Director of the US Patent and Trademark Office
P.O. Box 1450
Alexandria, VA 22313-1450

Sir:

INTRODUCTORY COMMENTS

The following preliminary amendments and remarks are respectfully submitted in connection with the above-identified application.

This amendment includes:

Amendments to the Abstract begins on page 2 of this paper.

Amendments to the Claims are reflected in the listing of claims which begins on page 3 of this paper.

Remarks/Arguments begin on page 4 of this paper.

Abstract of the Disclosure begin on page 5 of this paper.